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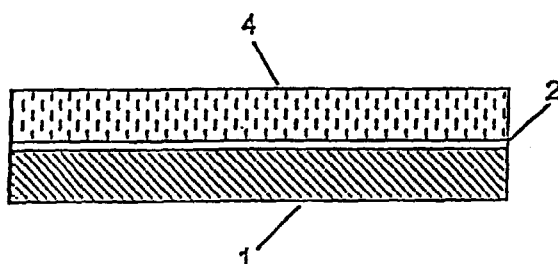
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(54) Title: A METHOD OF WAFER/SUBSTRATE BONDING



(57) Abstract: A method of bonding two components by depositing an amorphous and non-hydrogenated intermediate layer (2) on one of the components (1,4) and arranging the components (1,4) in spaced relationship with the intermediate layer (2) therebetween. The method further comprises heating one or both of the components (1,4) before bringing the components (1,4) into contact. Finally, a voltage is applied to the components (1,4) to create a permanent bond between the two components.



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